Features

- 3535 with integrated high quality constant current IC and RGB LED chip.
- Built-in IC, with high precision of constant current and internal RGB chips spectral processing in advance.
- Single line data transmission (return to zero code).
- Specific Shaping Transmit Technology - number of LED stacked is not restricted.
- Cascading Enhancement Technology - any 2 LED spacing can be up to 10 meters
- Data transfer rate of 800 kbp/s at 30 frames per second.
- RGB output port PWM control can achieve 256 grey level adjustments.
- Upon powering up, IC performs self-inspection then lights connection on the pin B lamp.
- SA-I Anti-interference patent technology for single line data transmission.
- Built-in power supply reverse connect protection module, reversed power input will not damage the IC.

Description

The IN-PI33TBTPRPGPB is 3.5*3.5*1.95mm RGB LED with integrated IC. It is a SMD type LED which can be used in various applications.

Applications

- Full color LED string light
- LED full color module
- LED guardrail tube
- LED scene lighting
- LED point light
- LED pixel screen
- LED shaped screen

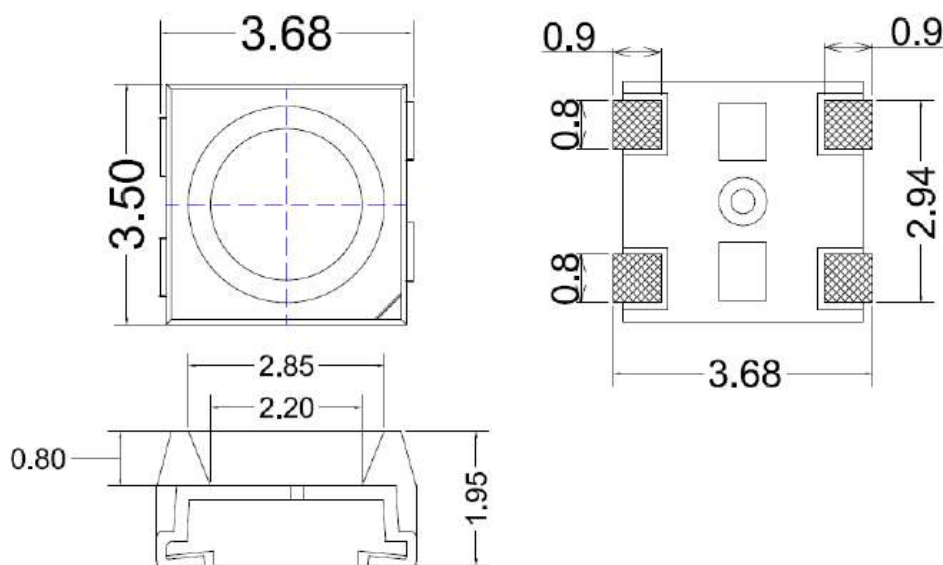## Package Outline Dimensions & Pin Configuration

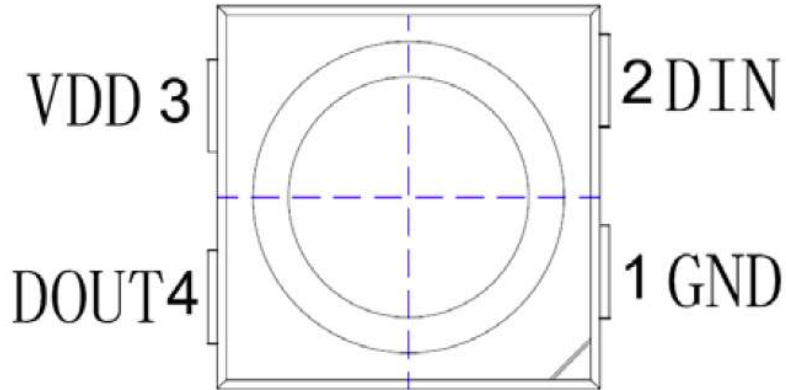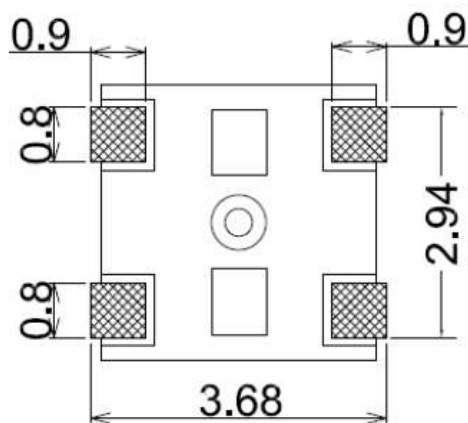**Figure 1. IN-PI33TBTPRPGPB Package Outline Dimensions**

Pin Configuration

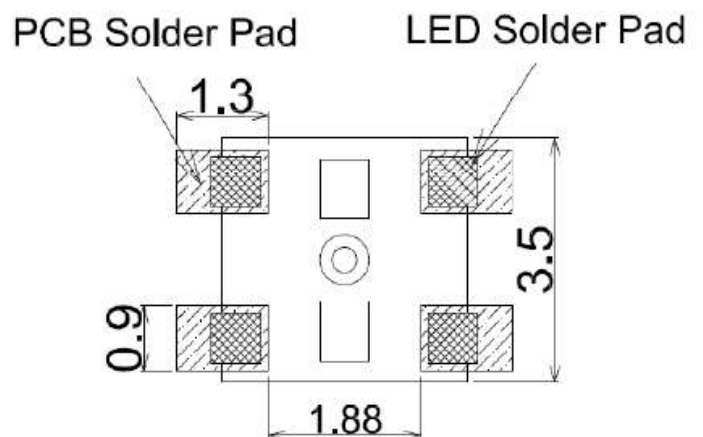

Figure 2. IN- PI33TBTPRPGPB Pin Configuration

Notes:
1. Dimension in millimeter, tolerance is ±0.1mm unless otherwise noted.

Number	Symbol	Function Description
1	GND	Ground
2	DIN	Control data signal input
3	VDD	Power supply LED
4	DOUT	Control data signal output

Soldering Pad Size

Pad Size

Steel mesh size

Absolute Maximum Rating *(Ta = 25 ℃, VSS=0V)*

Parameter	Symbol	Range	Unit
Logic supply voltage	V_{DD}	+3.5～+5.5	V
Logic input voltage	V_{IN}	-0.5 ~VDD+0.5	V
Operating temperature	T_{OPT}	−45 ~ +85	°C
Storage temperature	T_{STG}	−50 ~ +150	°C
ESD pressure(HBM)	V_{ESD}	4K	V
ESD pressure(DM)	V_{ESD}	200	V

LED Characteristics *(Ta = 25℃)*

Color	12mA	
	Wavelength(nm)	Light Intensity(mcd)
Red	620-630	400-700
Green	515-530	1000-1500
Blue	460-470	300-500

Recommended Operating Ranges *(unless otherwise specified, Ta= -20 ~ +70 ℃, VDD=4.5 ~ 5.5V,VSS=0V)*

Parameter	Symbol	Min.	Typ.	Max	Unit	Test conditions
Supply voltage	V_{DD}	-	5.2	-	V	-
R/G/B port pressure	$V_{DS, MAX}$	-	-	26	V	-
DOUT drive capability	ID_{OH}	-	49	-	mA	maximum source current
DOUT drive capability	ID_{OL}	-	-50	-	mA	maximum sink current
High level input voltage	V_{IH}	0.7*VDD	-		V	VDD=5.0V
Low level input voltage	V_{IL}	-	-	0.3*VDD	V	VDD=5.0V
The frequency of PWM	F_{PWM}	-	1.2	-	KHZ	-
Static power consumption	I_{DD}	-	1	-	mA	-

Switching Characteristics *(unless otherwise specified, Ta=25 ℃)*

Parameter	Symbol	Min.	Typ.	Max	Unit	Test conditions
The speed of data transmission	$fDIN$	-	800	-	KHZ	The duty ratio of 67% (data 1)
DOUT transmission delay	T_{PLH}	-	-	500	ns	DIN→DOUT
	T_{PHL}	-	-	500	ns	
I_{OUT} Rise/Drop Time	T_r	-	100	-	ns	V_{DS}=1.5 I_{OUT}=13mA
	T_f	-	100	-	ns	
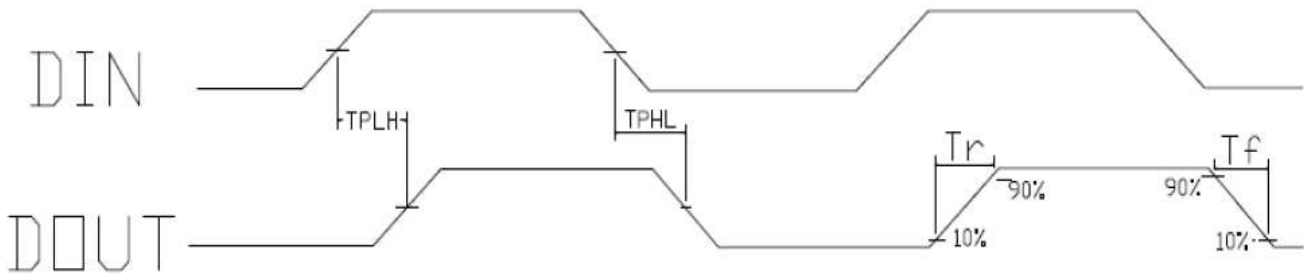
Timing Waveforms

1. Input Code
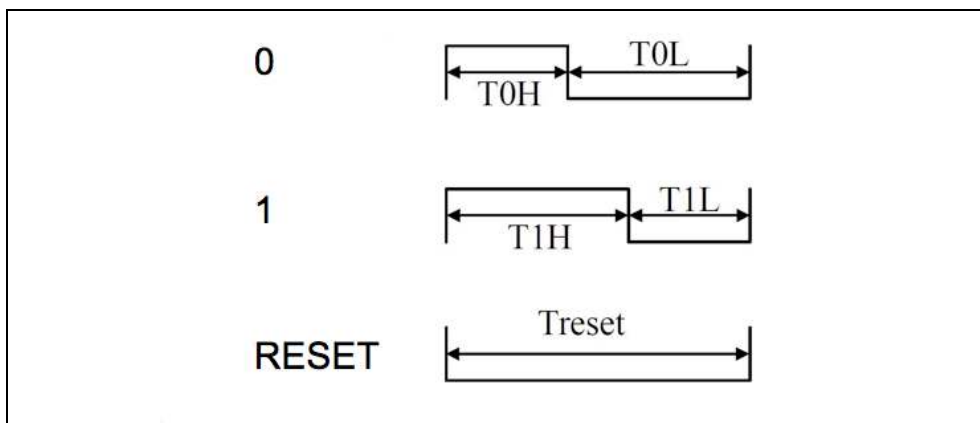
2. The data transmission time (TH+TL=1.25μs±600ns):

| Name	Description	Typ. value	error
T0H	0 code, high level time	0.3μs	±0.15μs
T0L	0 code, low level time	0.9μs	±0.15μs
T1H	1 code, high level time	0.9μs	±0.15μs
T1L	1 code, low level time	0.3μs	±0.15μs
Trst	Reset code, low level time	80μs	

3. Connection Scheme
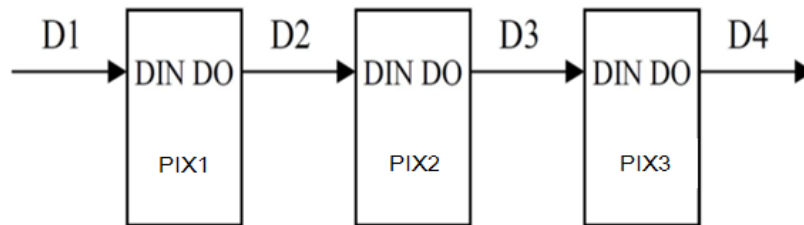
4. Data Transfer Format
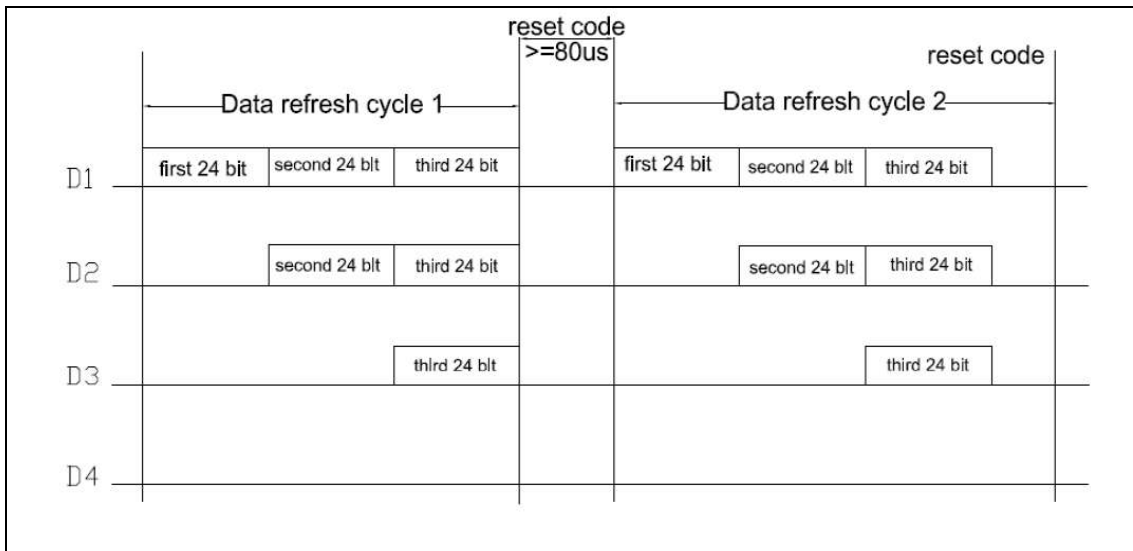
Note: the D1 sends data for MCU, D2, D3, D4 for data forwarding automatic shaping cascade circuit.

5. 24-bit data format
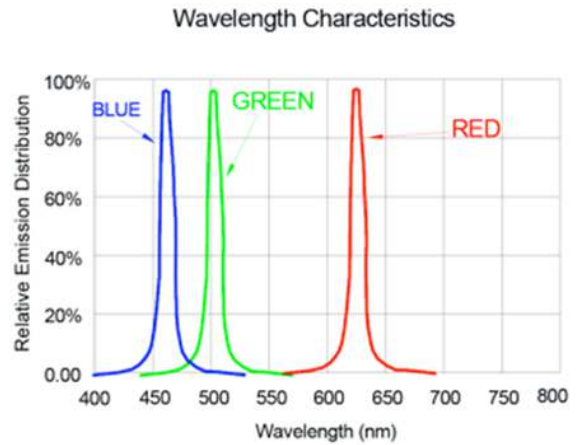

Note: high starting, in order to send data (G7 - G6 - ....B0)

Typical Application Circuit
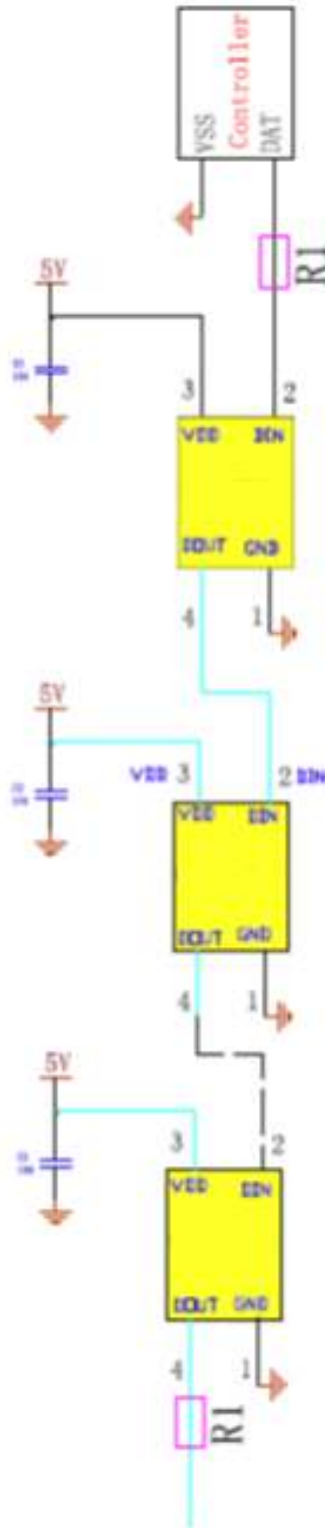
Product signal input and output must be connected in series with protection resistor R1. R1 depends on the size of the cascade amount, the greater the number of cascade, the smaller R1. The general recommended value is between 200-2KΩ, usually the recommended value is typical 500Ω.

LED Performance Graph

Thermal Pad Temperature vs. Relative Light Output

Wavelength Characteristics
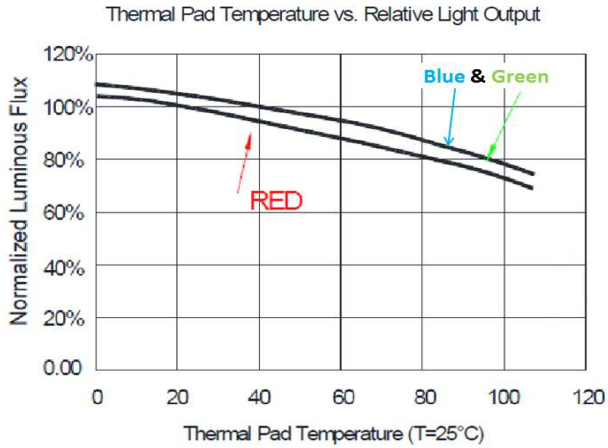
Typical Radiation Pattern   120°

Ordering Information

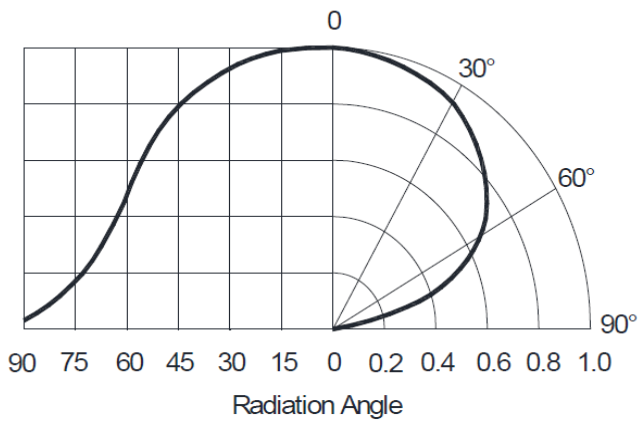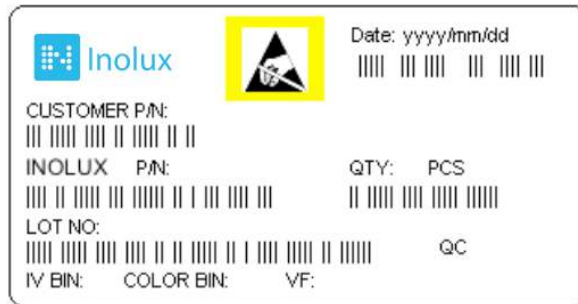| Product	Emission Color	IV(mcd)	Orderable Part Number
IN-PI33TBTPRPGPB	R	400-700	IN-PI33TBTPRPGPB
	G	1000-1500	
	B	300-500	

Label Specifications

Inolux

Date: yyyy/mm/dd

CUSTOMER P/N:

INOLUX   P/N: QTY: PCS

LOT NO: QC

IV BIN: COLOR BIN: VF:

Inolux P/N:

I	N	PI	-	33	T	B	T	(X)	R	(X)	G	(X)	B	-	X	X	X	X
		Product		Package	Die Qty.	Variation	Orientation	Current	Color	Current	Color	Current	Color		Customized Stamp-off			
	Inolux	PI- Single trace IC PC- Clock Function IC		33TB = 3.5 x 3.5 x 1.95 mm			T = Top Mount	P=12mA 5 = 5mA	R = 624 nm	P=12mA 5 = 5mA	G = 520 nm	P=12mA 5 = 5mA	B = 470 nm					

Lot No.:

Z	2	0	1	7	01	24	001
Internal Tracker	Year (2017, 2018, …..)				Month	Date	Serial

Precautions

Please read the following notes before using the product:

1. Storage

1.1 Do not open moisture proof bag before the products are ready to use.

1.2 Before opening the package, the LEDs should be kept at 30℃ or less and 80%RH or less.

1.3 The LEDs should be used within a year.

1.4 After opening the package, the remaining LEDs should be kept in a resealed bag.

1.5 The LEDs require mandatory baking before usage. Baking treatment listed below.

1.6 If the moisture adsorbent material has fabled away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.

*Baking treatment: 60±5℃ for24 hours.

2. Soldering Condition
Recommended soldering conditions:
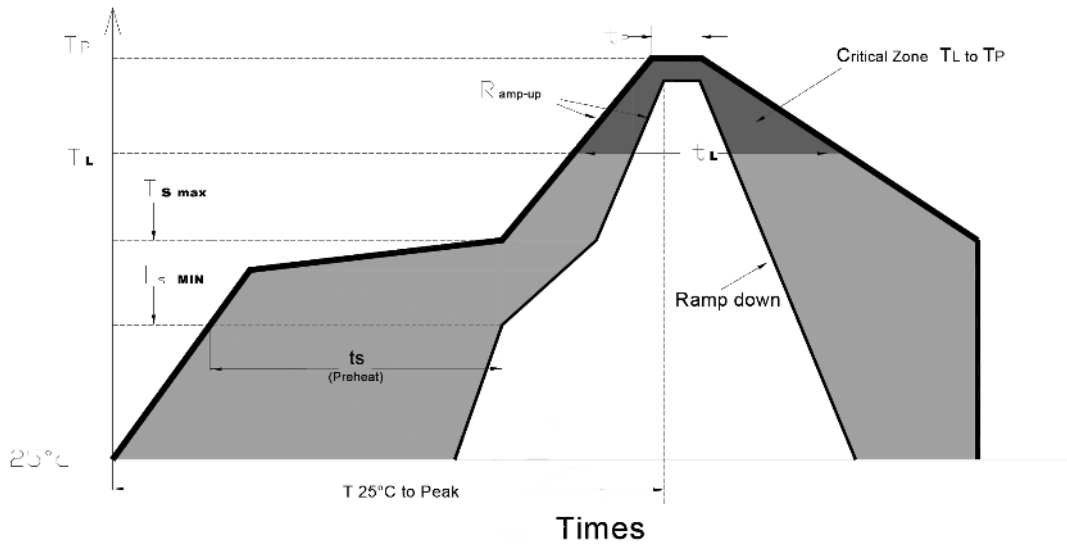
| Profile Feature	Lead-Free Solder
Average Ramp-Up Rate (Ts max to Tp)	3℃/second max.
Preheat: Temperature Min (Ts min)	150℃
Preheat: Temperature Min (Ts max)	200℃
Preheat: Time (ts min to ts max)	60-180 seconds
Time Maintained Above: Temperature (T_L)	217 ℃
Time Maintained Above: Time (t L)	60-150 seconds
Peak/Classification Temperature (T P)	240 ℃
Time Within 5℃ of Actual Peak Temperature (tp)	<10 seconds
Ramp-Down Rate	6℃/second max.
Time 25 ℃ to Peak Temperature	<6 minutes max.

Note: Excessive soldering temperature and / or time might result in deformation of the LED lens or catastrophic failure of the LED.

3. Soldering Iron

Each terminal is to go to the tip of soldering iron temperature less than 260℃ for 5 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

4. Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.
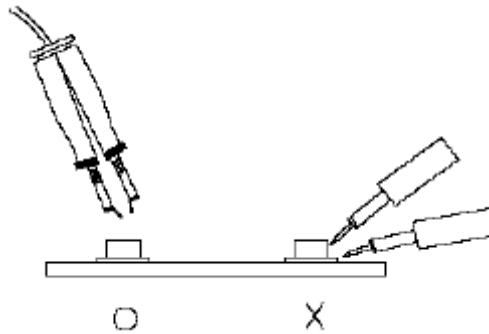
5. Caution in ESD

Static Electricity and surge damages the LED. It is recommended to use a wristband or anti-electrostatic glove when handling the LED. All devices, equipment and machinery must be properly grounded.

Revision History

Changes since last revision	Page	Version No.	Revision Date
Initial Release		1.0	05-31-2018
Format Adjustment		1.1	07-01-2018
Revise precautions	10	1.2	07-31-2019

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2. A critical component in any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.